Title (en)

COPPER ALLOY SHEET MATERIAL AND PROCESS FOR PRODUCING SAME

Title (de)

KUPFERLEGIERUNGSFOLIENMATERIAL UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)

MATÉRIAU EN FEUILLE D'ALLIAGE DE CUIVRE ET SON PROCÉDÉ DE FABRICATION

Publication

EP 2612934 A1 20130710 (EN)

Application

EP 11821733 A 20110829

Priority

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- JP 2011069467 W 20110829

Abstract (en)

{Problems} To provide a copper alloy sheet material and a method of producing the same, which sheet material is excellent in a bending property, and has an excellent mechanical strength, and which is suitable for lead frames, connectors, terminal materials, and the like in electrical/electronic equipments, for connectors, for example, to be mounted on automotive vehicles, and for terminal materials, relays, switches, and the like. {Means to solve} A copper alloy sheet material, containing Ti in an amount of 1.0 to 5.0 mass%, with the balance being copper and unavoidable impurities, wherein an area ratio of Cube orientation {0 0 1} <1 0 0> is 5 to 50%, in crystal orientation analysis by an EBSD analysis in the sheet thickness of the sheet material; and a method of producing the same.

IPC 8 full level

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CPC (source: CN EP)

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